



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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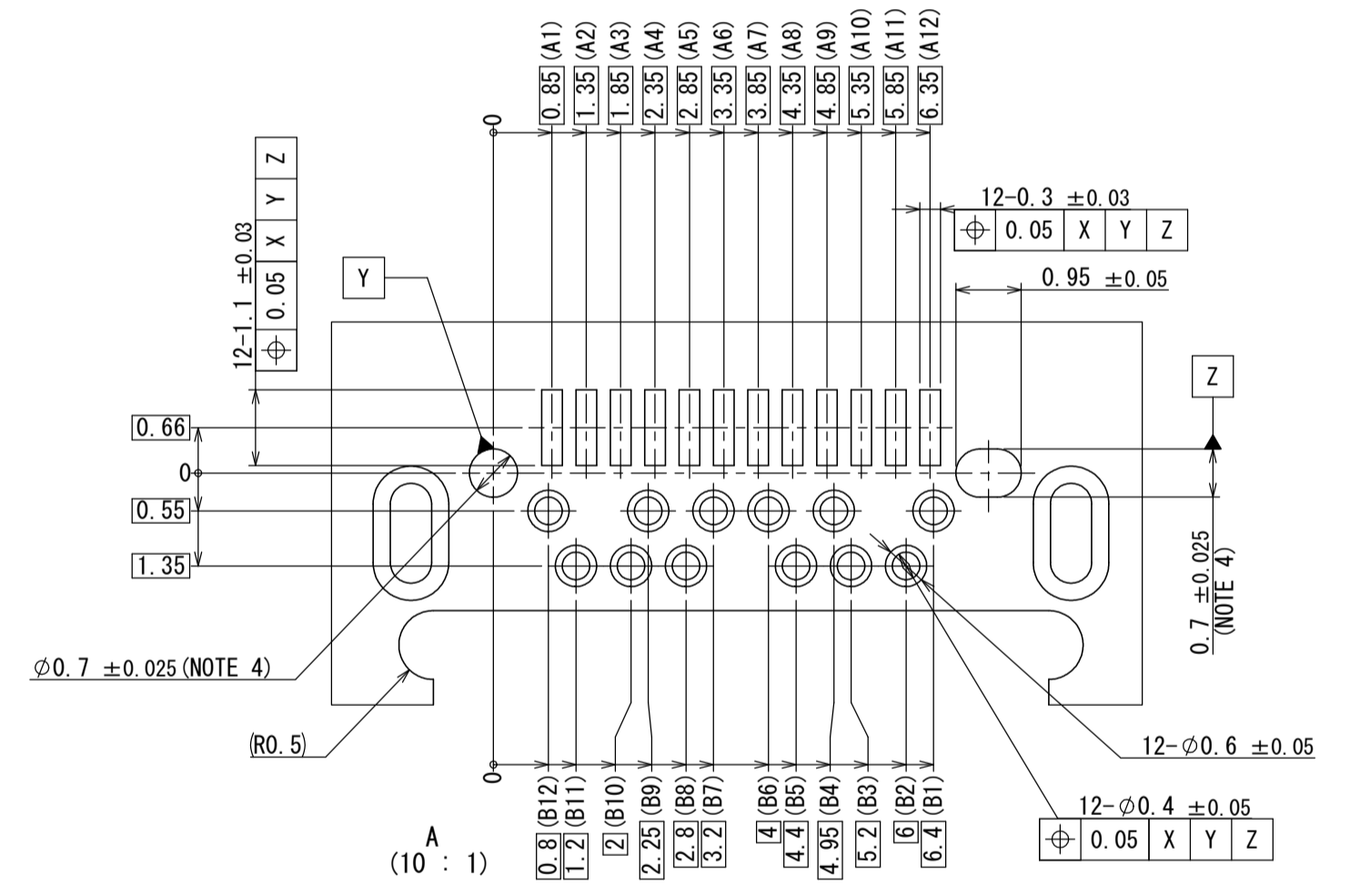
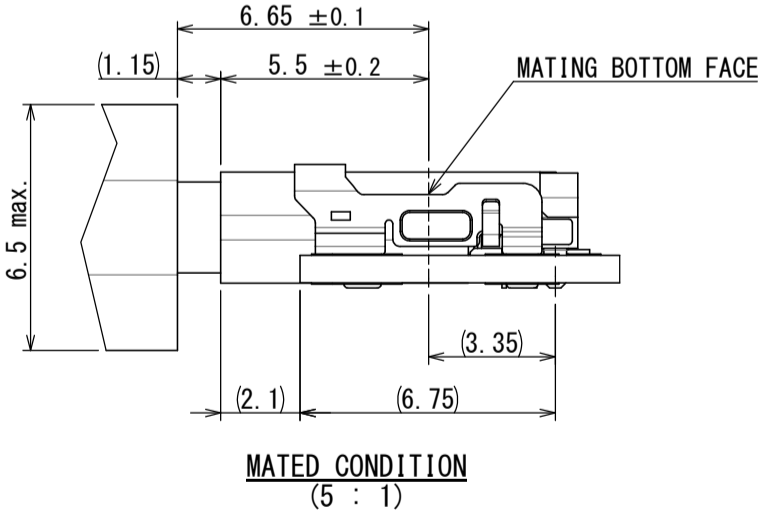
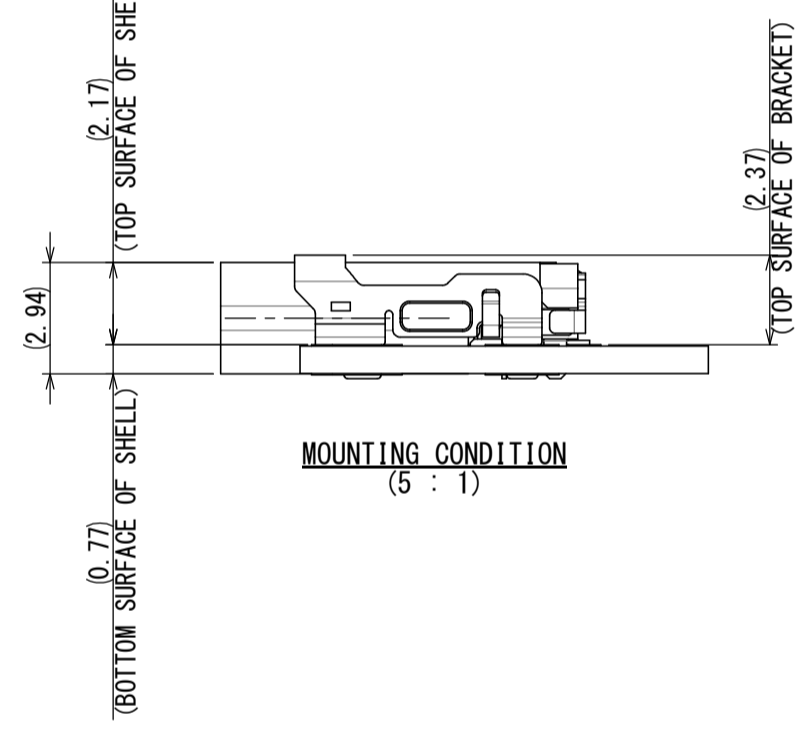
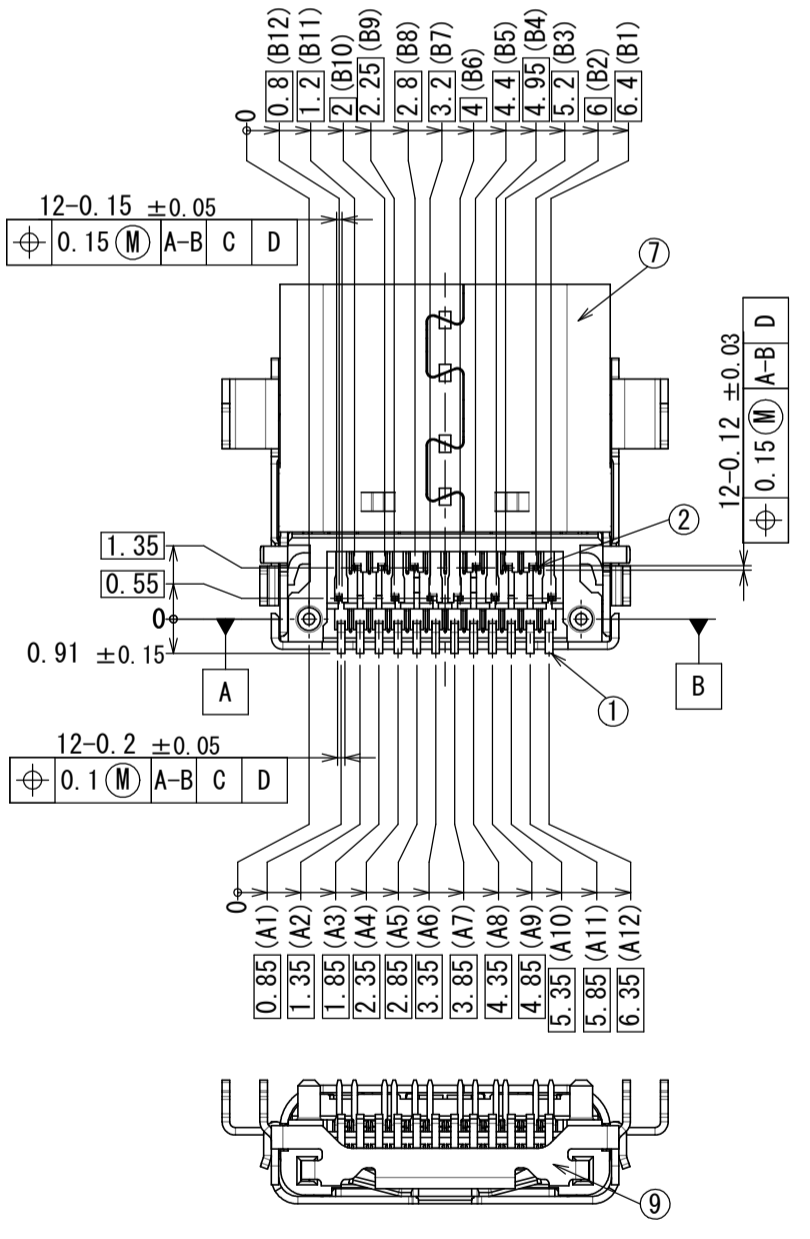
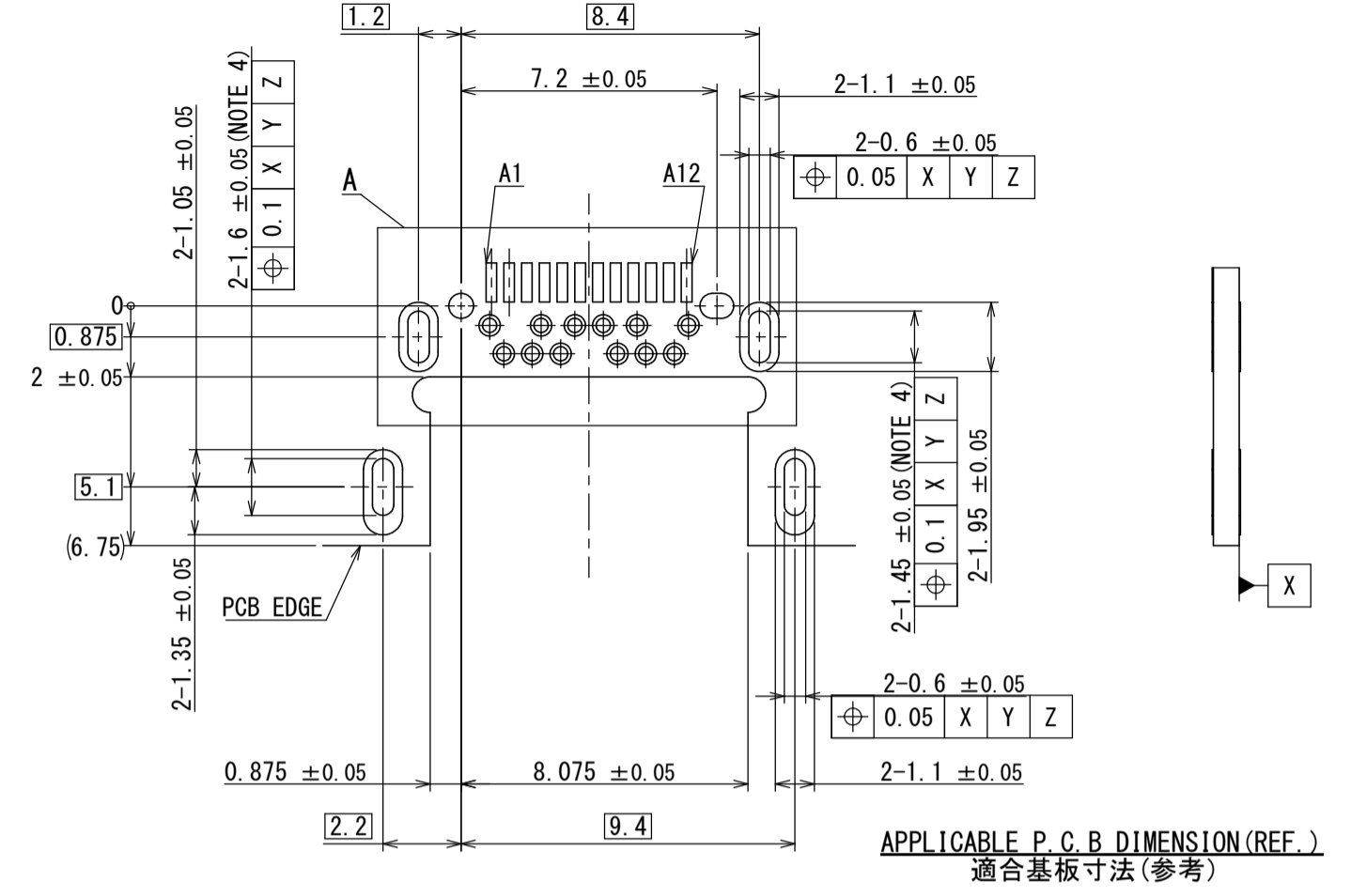
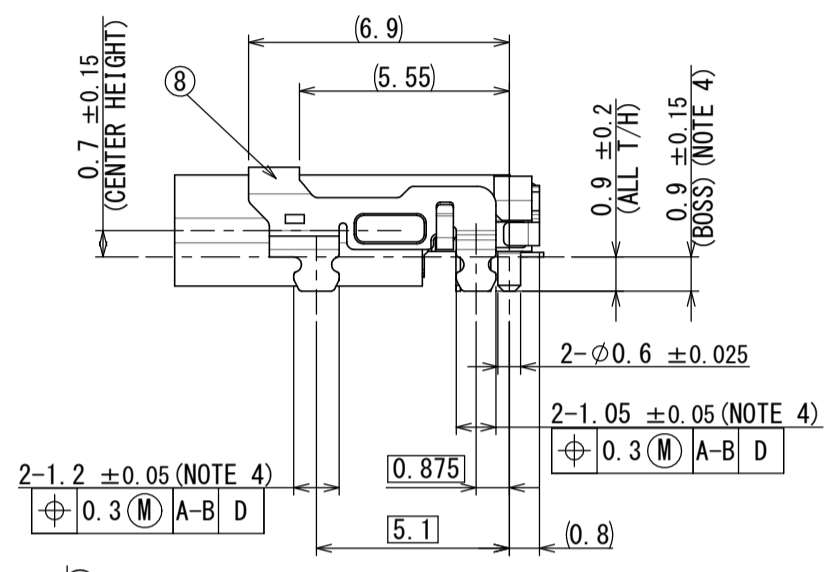
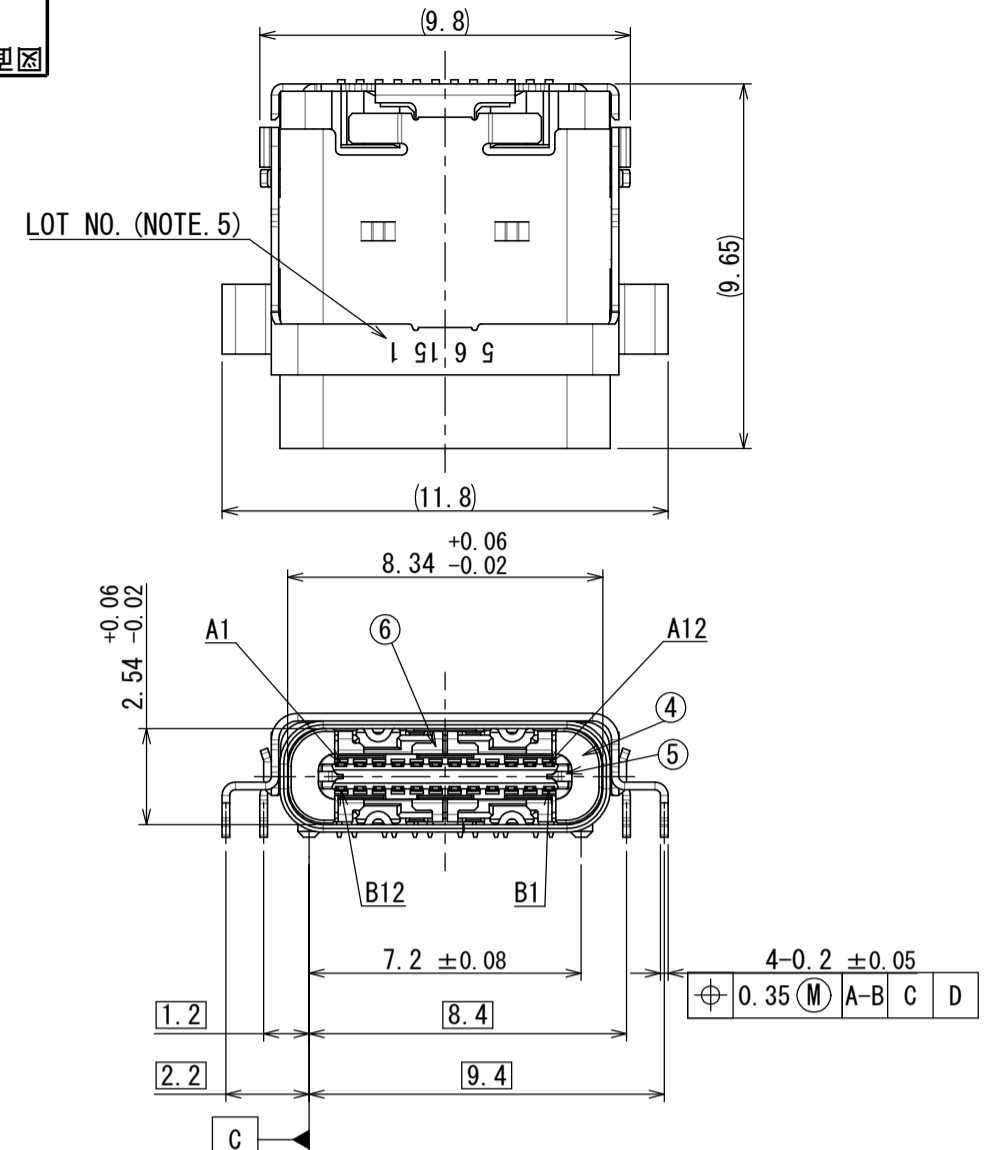


TABLE 2. PIN DEFINE

A12	GND	B1	GND
A11	SSRXp2	B2	SSTXp2
A10	SSRXn2	B3	SSTXn2
A9	VBUS	B4	VBUS
A8	SUB1	B5	CC2
A7	Dn1	B6	Dp2
A6	Dp1	B7	Dn2
A5	CC1	B8	SUB2
A4	VBUS	B9	VBUS
A3	SSTXn1	B10	SSRXn1
A2	SSTXp1	B11	SSRXp1
A1	GND	B12	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

TABLE 1

	FINISH	PLATING THICKNESS
CONTACT AREA	GOLD FLASH OVER PALLADIUM-NICKEL OVER NICKEL	NICKEL: 2 μm MIN. PALLADIUM-NICKEL: 0.75 μm MIN. GOLD FLASH: 0.05 μm MIN.
SOLDER TALES	GOLD FLASH OVER NICKEL	NICKEL: 2 μm MIN. GOLD FLASH: 0.03 μm MIN.

符号 No.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
9	REAR SHIELD	1	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS: 1 μm Min.
8	BRACKET	1	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS: 1 μm Min.
7	SHELL	1	STAINLESS STEEL	BLACK NICKEL PLATING	PLATING THICKNESS: 1 μm Min.
6	GND PLATE	2	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS: 1 μm Min.
5	GND MID PLATE	1	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS: 1 μm Min.
4	INSULATOR	1	THERMOPLASTIC RESIN	COLOR: BLACK	HALOGEN-FREE
3	CONTACT C	6	COPPER ALLOY	TABLE 1	
2	CONTACT B	6	COPPER ALLOY	TABLE 1	
1	CONTACT A	12	COPPER ALLOY	TABLE 1	

NOTE 1. COPLANARITY OF SMT TERMINAL IS 0.1 MAX  
 NOTE 2. RECOMMENDED METAL MASK THICKNESS: 120 μm  
 NOTE 3. THE SHELL LENGTH IS LESS THAN THE MINIMUM SPECIFIED BY THE USB STANDARD.  
 AS SUCH IT CANNOT INDEPENDENTLY BE GUARANTEED TO MEET ALL TYPE C MECHANICAL REQUIREMENTS.  
 THE SYSTEM IMPLEMENTER IS RESPONSIBLE FOR ACHIEVING PRODUCT RELIABILITY AND PASSING USB COMPLIANCE TESTING.  
 REFERENCE THE USB TYPE C SPECIFICATION RELEASE 1.1, SECTION 3.2.1, NOTE 7.  
 NOTE 4. CONNECTOR MAY NOT BE GUIDED TO PROPER POSITION ON PCB WITH THIS LENGTH OF GUIDE POSTS AND THE SIZE OF EACH HOLE.  
 IT MAY CAUSE MOUNTING FAILURE.  
 NOTE 5. LOT NUMBER IS MARKED AS INDICATED.

(EX) 5 6 15 1  
 EQUIPMENT No. (NUMBER OR ALPHABET)  
 DAY (TWO-DIGITS NUMBER)  
 MONTH (NUM. TO SEP.: 1 TO 9, OCT.: 0, NOV.: X, DEC.: Y)  
 YEAR (END OF DIGIT AT CHRISTIAN ERA)

仕様書(SPECIFICATION)	第1版(ORIGINAL DATE) 16/JUN/2015	尺度(SCALE) 5:1	シリーズ(SERIES) DX07	日本航空電子工業株式会社
一般公差(GENERAL TOLERANCE)	製図 DR.	名称(TITLE) DX07B024XJ1		JAE JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
寸法(DIMENSION): ±0.8 × ±0.4 ×× ±0.1 ××× ±	担当 CHK. M. SASAKI	質量(MASS)		
角度(ANGLES): ×° ± ××' ±	査閲 APPD.	単位(UNIT): mm		図面番号(DRAWING NO.) SJ116121
	承認 APPD. T. MASUMOTO			版数 (VER.) 1